

FDR8321L

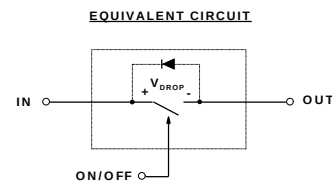
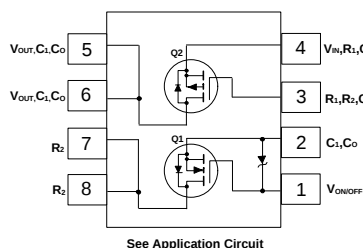
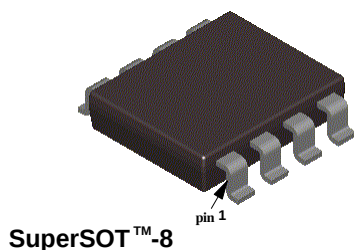
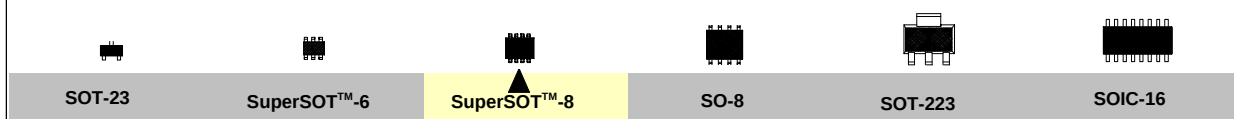
P-Channel MOSFET With Gate Driver For Load Switch Application

General Description

This device is designed for configuration as a load switch and is particularly suited for Power Management in portable battery powered electronic equipment. Designed to operate from 2.5V to 8V input and supply up to 2.9A. The device features a small N-Channel MOSFET (Q1) together with a large P-Channel power MOSFET (Q2) in a single SuperSOT™-8 package.

Features

- $V_{DROP} = 0.2V$ @ $V_{IN} = 5V$, $I_L = 2.9A$. $R_{DS(ON)} = 0.070 \Omega$
 $V_{DROP} = 0.2V$ @ $V_{IN} = 2.5V$, $I_L = 2A$. $R_{DS(ON)} = 0.105 \Omega$.
- $V_{ON/OFF}$ Zener protection for ESD ruggedness (>6KV Human Body Model).
- High density cell design for extremely low on-resistance.



Absolute Maximum Ratings $T_A = 25^\circ C$ unless otherwise noted

Symbol	Parameter	FDR8321L	Units
V_{IN}	Input Voltage Range	2.5 - 8	V
$V_{ON/OFF}$	On/Off Voltage Range	1.5 - 8	V
I_L	Load Current @ $V_{DROP} = 0.2V$ - Continuous (Note 1)	2.9	A
		10	
P_D	Maximum Power Dissipation (Note 2)	0.8	W
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to 150	$^\circ C$

THERMAL CHARACTERISTICS

$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (Note 2)	156	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case (Note 2)	40	$^\circ C/W$

Electrical Characteristics (T_A = 25°C unless otherwise noted)

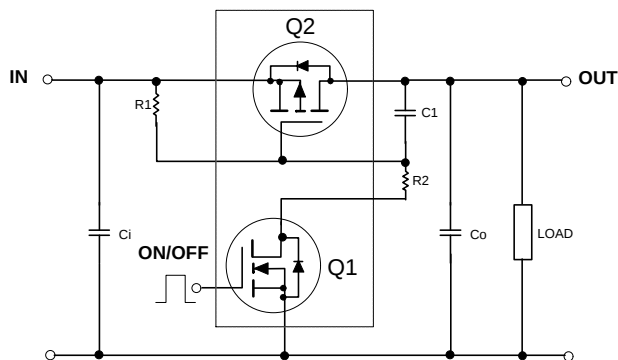
Symbol	Parameter	Conditions	Min	Typ	Max	Units
OFF CHARACTERISTICS						
I _{FL}	Forward Leakage Current	V _{IN} = 5 V, V _{ON/OFF} = 0 V			1	μA
ON CHARACTERISTICS (Note 3)						
V _{DROP}	Conduction Voltage Drop	V _{IN} = 5 V, V _{ON/OFF} = 3.3 V, I _L = 2.9 A		0.185	0.2	V
		V _{IN} = 2.5 V, V _{ON/OFF} = 3.3 V, I _L = 2 A		0.18	0.2	
R _{DS(ON)}	Q ₂ - Static Drain-Source On-Resistance	V _{GS} = -5 V, I _D = -2.9 A		0.06	0.07	Ω
		V _{GS} = -2.5 V, I _D = -2 A		0.09	0.105	
I _L	Load Current	V _{DROP} = 0.2 V, V _{IN} = 5 V, V _{ON/OFF} = 3.3 V	2.9			A
		V _{DROP} = 0.2 V, V _{IN} = 2.5 V, V _{ON/OFF} = 3.3 V	2			

Notes:

- V_{IN}=5V, V_{ON/OFF}=8V, V_{DROP}=0.2V, T_A=25°C
- R_{θJA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{θJC} is guaranteed by design while R_{θCA} is determined by the user's board design. R_{θJA} typical =156°C/W when mounted on a minimum 0.0025 in² pad on FR-4.
- Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2.0%

FDR8321L Load Switch Application

APPLICATION CIRCUIT



External Component Recommendation

First select R2, 100 - 1kΩ, for Slew Rate control.

C1 ≤ 1000pF can be added in addition to R2 for further In-rush current control.

Then select R1 such that R1/R2 ratio maintains between 10 - 100. R1 is required to turn Q2 off.

For SPICE simulation, users can download a "FDR8321L.MOD" Spice model from Fairchild Web Site at www.fairchildsemi.com

Typical Electrical Characteristics ($T_A = 25^\circ\text{C}$ unless otherwise noted)

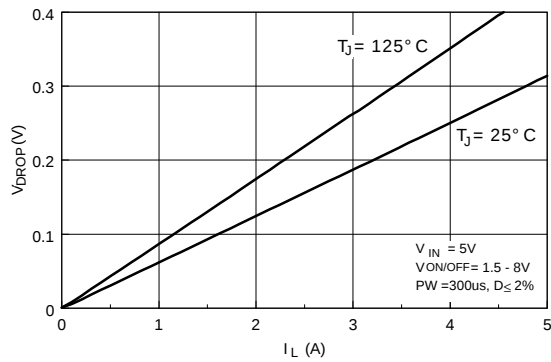


Figure 1. Conduction Voltage Drop versus Load Current at Input Voltage 5V.

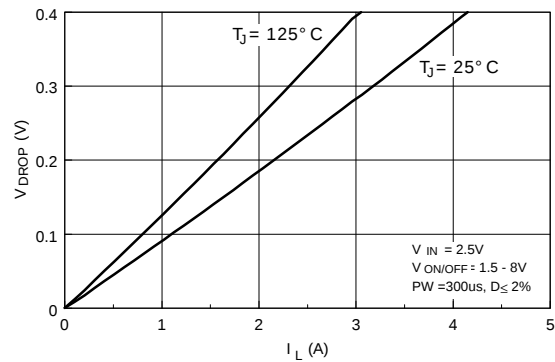


Figure 2. Conduction Voltage Drop versus Load Current at Input Voltage 2.5V.

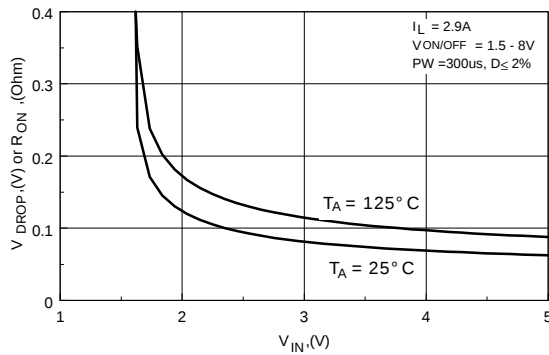


Figure 3. Conduction Voltage Drop versus input Voltage at Load Current 2.9A.

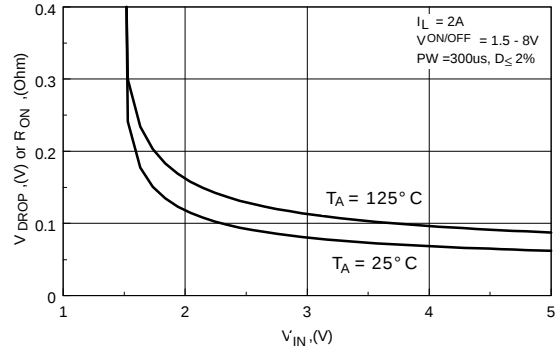


Figure 4. Conduction Voltage Drop versus Input Voltage at Load Current 2A.

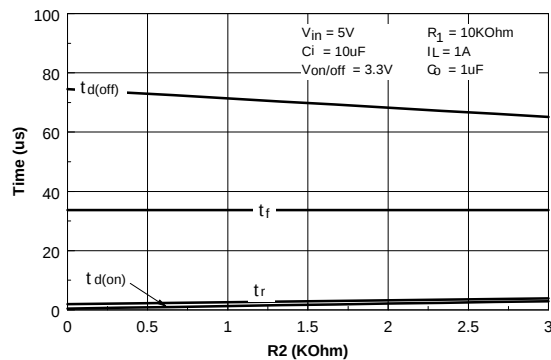


Figure 5. Switching Variation with R_2 at $V_{in} = 5V$ and $R_1 = 10K\Omega$.

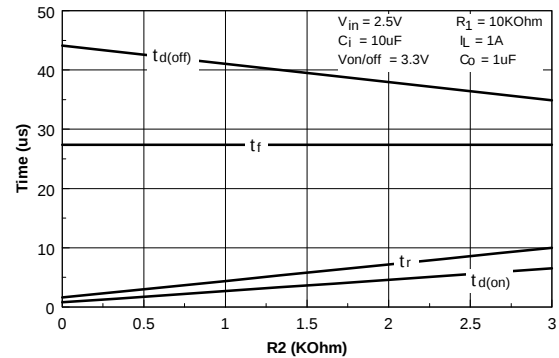


Figure 6. Switching Variation with R_2 at $V_{in} = 2.5V$ and $R_1 = 10K\Omega$.

Typical Electrical Characteristics ($T_A = 25\text{ }^{\circ}\text{C}$ unless otherwise noted)

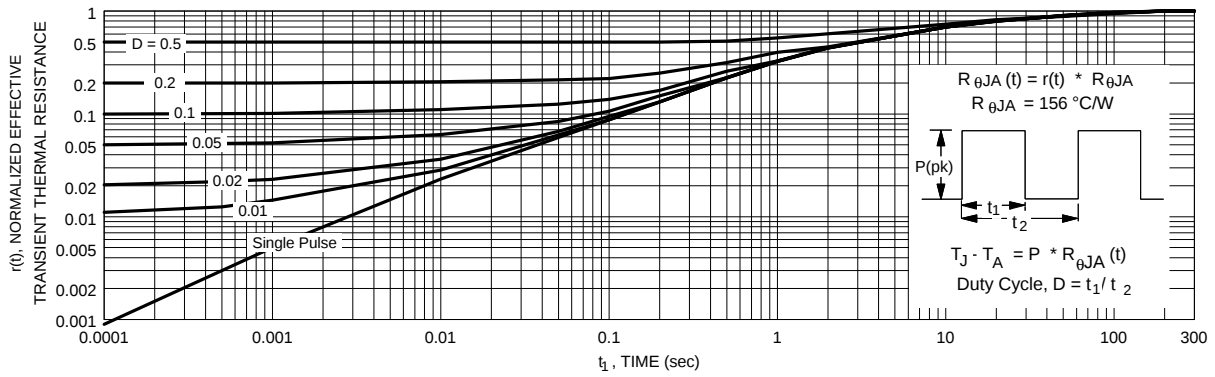


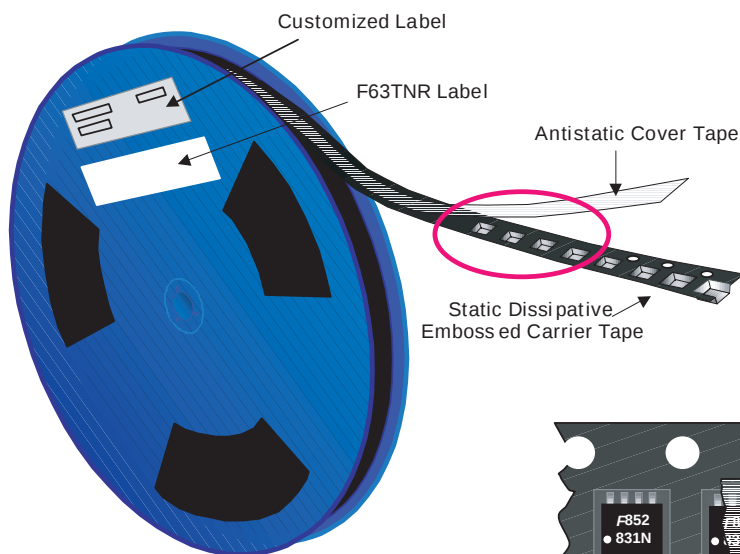
Figure 7. Transient Thermal Response Curve.

Thermal characterization performed on the conditions described in Note 2.

SuperSOT™-8 Tape and Reel Data and Package Dimensions



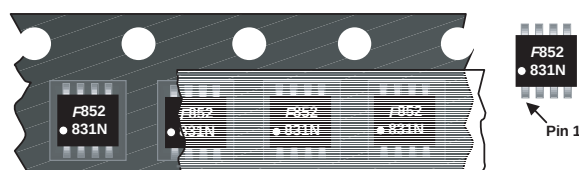
SSOT-8 Packaging Configuration: Figure 1.0



Packaging Description:

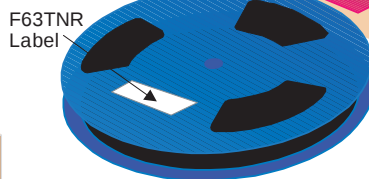
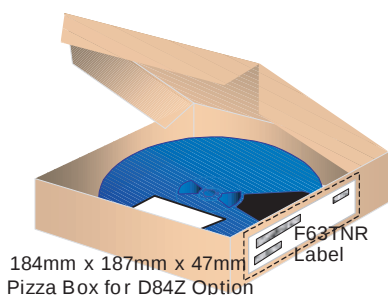
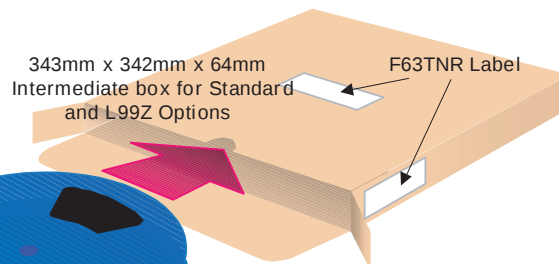
SSOT-8 parts are shipped in tape. The carrier tape is made from a dissipative (carbon filled) polycarbonate resin. The cover tape is a multilayer film (Heat Activated Adhesive in nature) primarily composed of polyester film, adhesive layer, sealant, and anti-static sprayed agent. These reeled parts in standard option are shipped with 3,000 units per 13" or 330cm diameter reel. The reels are dark blue in color and is made of polystyrene plastic (anti-static coated). Other option comes in 500 units per 7" or 177cm diameter reel. This and some other options are further described in the Packaging Information table.

These full reels are individually barcode labeled and placed inside a standard intermediate box (illustrated in figure 1.0) made of recyclable corrugated brown paper. One box contains two reels maximum. And these boxes are placed inside a barcode labeled shipping box which comes in different sizes depending on the number of parts shipped.



SSOT-8 Unit Orientation

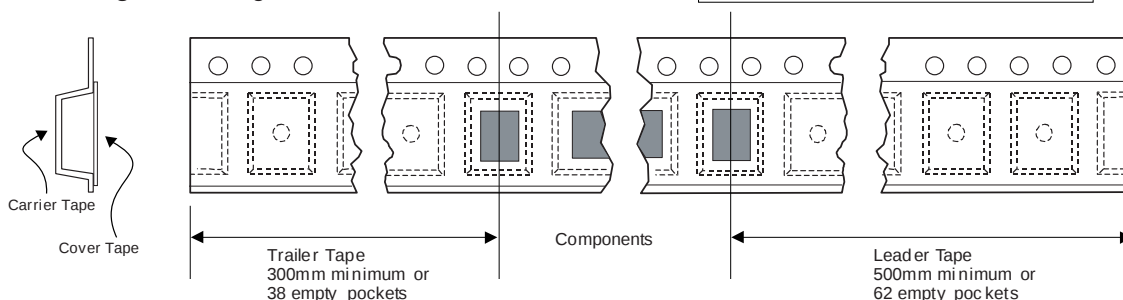
SSOT-8 Packaging Information		
Packaging Option	Standard (no flow code)	D84Z
Packaging type	TNR	TNR
Qty per Reel/Tube/Bag	3,000	500
Reel Size	13" Dia	7" Dia
Box Dimension (mm)	343x64x343	184x187x47
Max qty per Box	6,000	1,000
Weight per unit (gm)	0.0416	0.0416
Weight per Reel (kg)	0.5615	0.0980
Note/Comments		



F63TNR Label sample

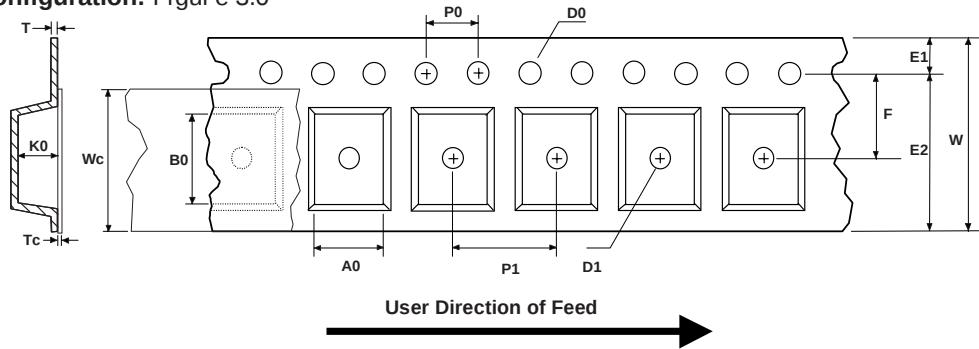


SSOT-8 Tape Leader and Trailer Configuration: Figure 2.0



SuperSOT™-8 Tape and Reel Data and Package Dimensions, continued

SSOT-8 Embossed Carrier Tape Configuration: Figure 3.0

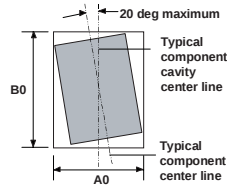


Dimensions are in millimeter														
Pkg type	A0	B0	W	D0	D1	E1	E2	F	P1	P0	K0	T	Wc	Tc
SSOT-8 (12mm)	4.47 +/-0.10	5.00 +/-0.10	12.0 +/-0.3	1.55 +/-0.05	1.50 +/-0.10	1.75 +/-0.10	10.25 min	5.50 +/-0.05	8.0 +/-0.1	4.0 +/-0.1	1.37 +/-0.10	0.280 +/-0.150	9.5 +/-0.025	0.06 +/-0.02

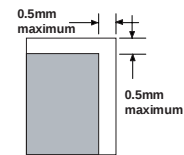
Notes: A0, B0, and K0 dimensions are determined with respect to the EIA/Jedec RS-481 rotational and lateral movement requirements (see sketches A, B, and C).



Sketch A (Side or Front Sectional View)
Component Rotation

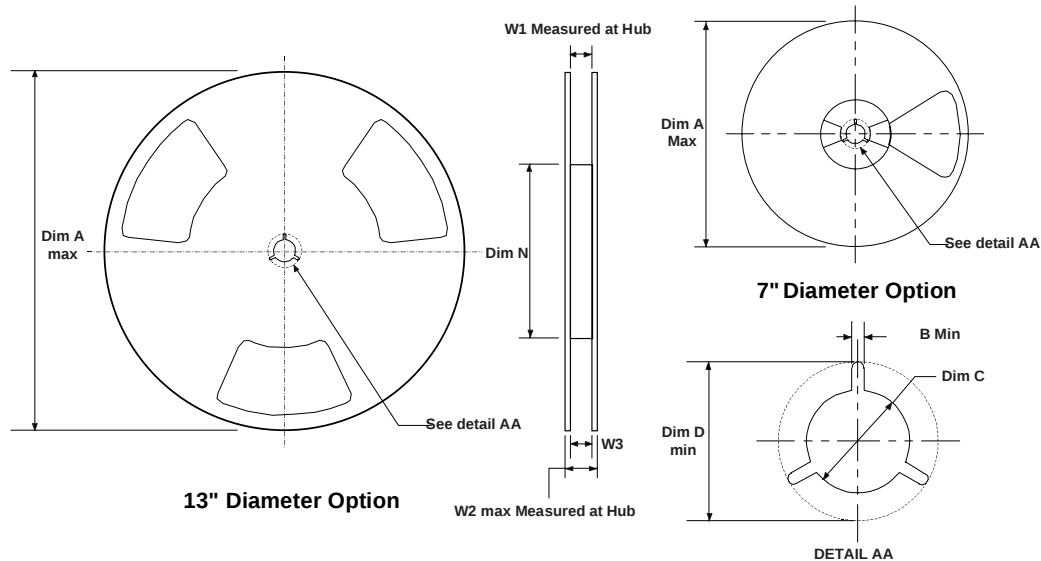


Sketch B (Top View)
Component Rotation



Sketch C (Top View)
Component lateral movement

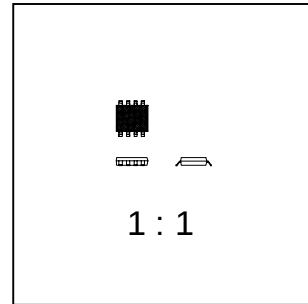
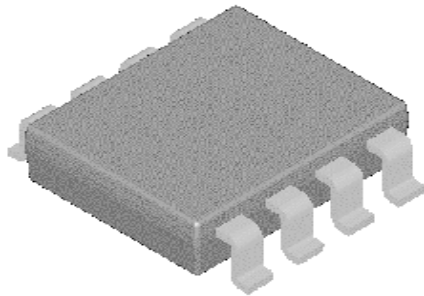
SSOT-8 Reel Configuration: Figure 4.0



Dimensions are in inches and millimeters									
Tape Size	Reel Option	Dim A	Dim B	Dim C	Dim D	Dim N	Dim W1	Dim W2	Dim W3 (LSL-USL)
12mm	7" Dia	7.00 177.8	0.059 1.5	512 +0.020/-0.008 13 +0.5/-0.2	0.795 20.2	5.906 150	0.488 +0.078/-0.000 12.4 +2/0	0.724 18.4	0.469 - 0.606 11.9 - 15.4
12mm	13" Dia	13.00 330	0.059 1.5	512 +0.020/-0.008 13 +0.5/-0.2	0.795 20.2	7.00 178	0.488 +0.078/-0.000 12.4 +2/0	0.724 18.4	0.469 - 0.606 11.9 - 15.4

SuperSOT™-8 Tape and Reel Data and Package Dimensions, continued

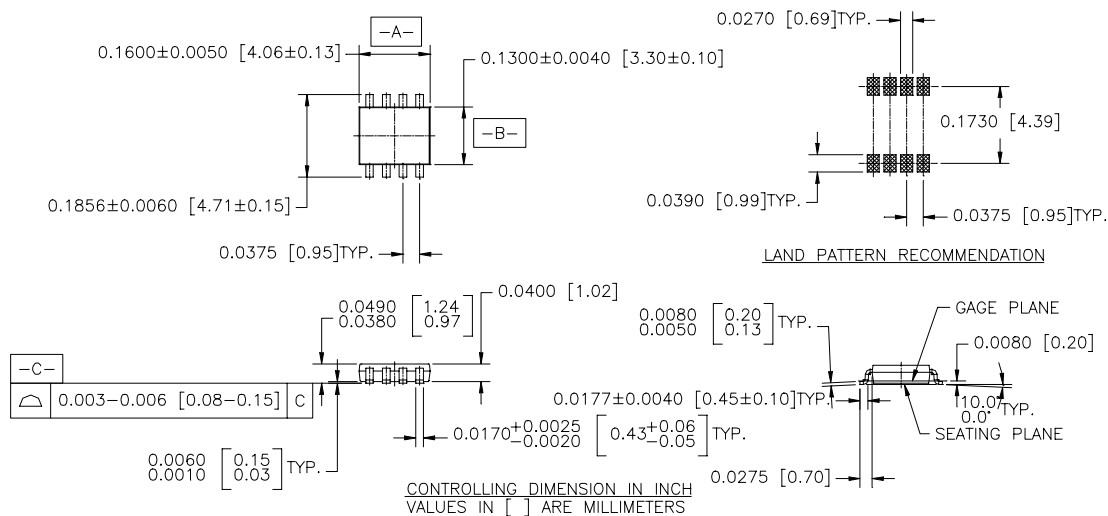
SuperSOT™-8 (FS PKG Code 34, 35)



Scale 1:1 on letter size paper

Dimensions shown below are in:
inches [millimeters]

Part Weight per unit (gram): 0.0416



NOTES : UNLESS OTHERWISE SPECIFIED

1. STANDARD LEAD FINISH TI BE 200 MICROINCHES / 5.08 MICROMETERS
MINIMUM TIN/LEAD (SOLDER) ON COPPER.
2. NO JEDEC REGISTRATION AS JAN. 1996

SUPER SOT, 8 LEADS

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